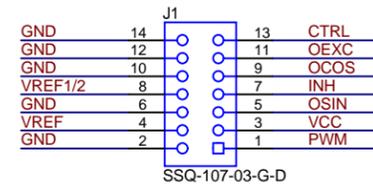
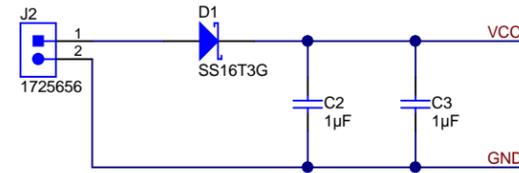
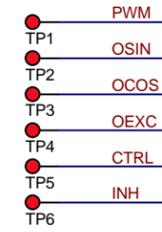


C2000 LaunchPadXL TMS320F28069M adapter for TIDA-01527

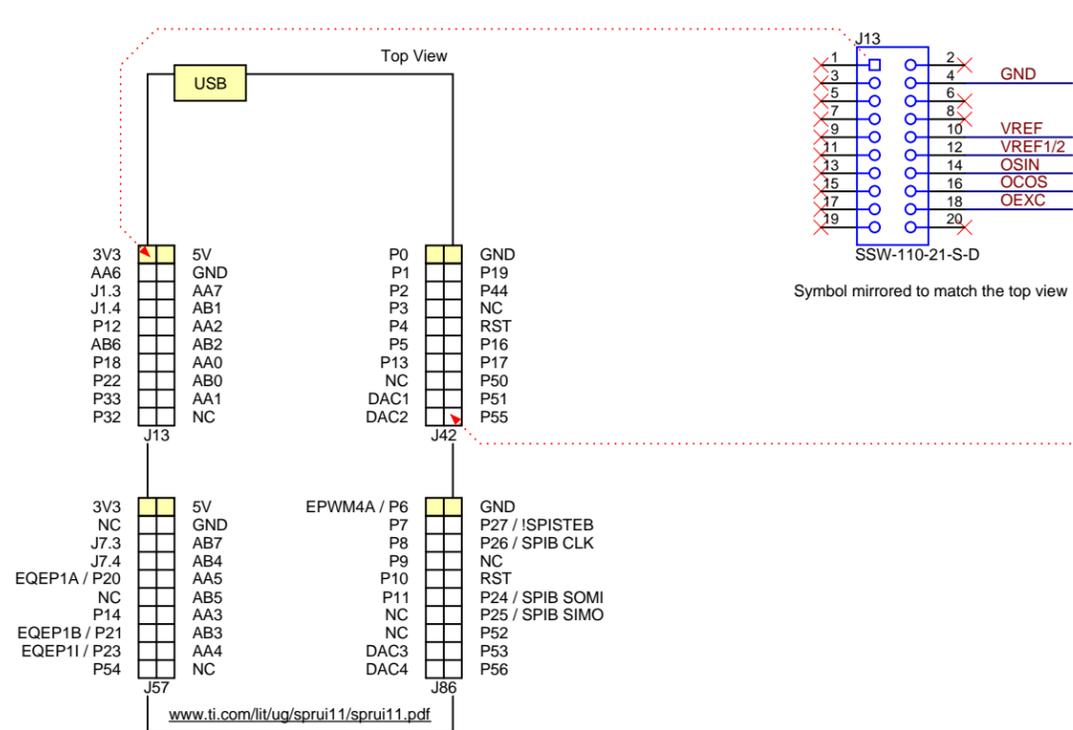


Symbol mirrored to match the bottom TIDA-01527 view

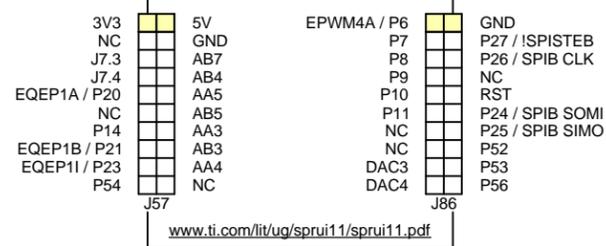
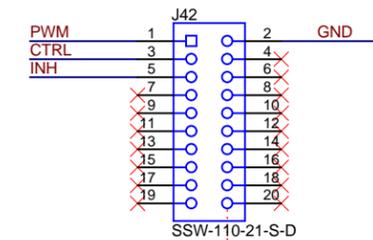


TIDA-01527

C2000 LaunchPadXL TMS320F28069M



Symbol mirrored to match the top view



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Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 04-Dec-17
TID #:	Project Title: TIDA-01527 Launchpad Adapter	
Number: TIDA-01527	Rev: E1	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By:	File: TIDA-01527 - Launchpad Adapter circuit.SchDoc	Size: B
Engineer: Jiri Panacek	Contact: http://www.ti.com/support	



PCB Number: TIDA-01527
PCB Rev: E1

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: ChangeMe!	Designed for: Public Release	Mod. Date: 13-Mar-18	 http://www.ti.com <small>© Texas Instruments 2017</small>
TID #: TIDA-01527	Project Title: TIDA-01527 Launchpad Adapter	Sheet Title:	
Number: TIDA-01527	Rev: E1	Assembly Variant: 001	
SVN Rev: Version control disabled	File: TIDA-01527 - Launchpad Adapter_Hardware.Sch	Sheet: 3 of 3	
Drawn By: Jiri Panacek	Engineer: Jiri Panacek	Contact: http://www.ti.com/support	

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